

Merit

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*This certificate is granted and awarded by the authority of the MedAccred Management Council to:*

## ***Benchmark Electronics, Inc.***

***3535 Technology Dr NW  
Rochester, MN 55901  
United States***

*This certificate demonstrates conformance and recognition of accreditation for specific services, as listed in [www.eAuditNet.com](http://www.eAuditNet.com) on the Qualified Manufacturer's List (QML), to the revision in effect at the time of the audit for:*

## ***Printed Board Assemblies***

Certificate Number: 87782007943  
Expiration Date: 31 August 2027  
Accreditation Length: 18 Months

A handwritten signature in black ink, appearing to read "Jay Solomond".

**Jay Solomond**  
Executive Vice President & Chief Operating Officer

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Performance Review Institute (PRI) | 161 Thorn Hill Road | Warrendale, PA 15086-7527

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## SCOPE OF ACCREDITATION

### Printed Board Assemblies

**Benchmark Electronics, Inc.**  
3535 Technology Dr NW  
Rochester, MN 55901

This certificate expiration is updated based on periodic audits. The current expiration date and scope of accreditation are listed at: [www.eAuditNet.com](http://www.eAuditNet.com) - Online QML (Qualified Manufacturer Listing).

In recognition of the successful completion of the PRI evaluation process, accreditation is granted to this facility to perform the following:

### **AC8120 Rev B - MedAccred Audit Criteria for Printed Circuit Board Assemblies (to be used on audits on/AFTER 05-Mar-2023)**

04.0 General

05.0 Process Validation

06.0 Medical Record Keeping

6.1 Device Master Record (DMR)

6.2 Device History Record (DHR)

6.3 Product Traceability

07.0 Foreign Object Damage and Foreign Object Debris (FOD) Prevention

08.0 Electrostatic Discharge (ESD) Management

09.0 Calibration

10.0 Preventive Maintenance

12.0 Purchasing and Authentic Component Assurance

13.0 Process Control

14.0 CAD/CAM Data

15.0 Receipt, Inspection & Control of Incoming Material

16.0 Storage and Handling of Received Materials

18.0 Electronic Component Preparation

19.0 Stencil Printing

20.0 Component Placement

20.1 Manual

20.3 Automated Part Placement

20.4 Build Through / Build Short

20.5 Through Hole Component Lead Trimming

21.0 In-Process Placement Verification / Inspection

21.1 General

21.2 Visual

21.3 Automated Optical Inspection (AOI)

21.4 X-Ray

22.0 Assembly Soldering Processes

22.1 Reflow Soldering

22.2 Wave Soldering

22.3 Selective Soldering

22.4 Hand Soldering

23.0 Secondary Assembly

23.1 Mechanical Part Installation

23.5 Compliant Pin (Press Fit) Connector Installation

24.0 PCBA Cleaning Process and Control

25.0 Coating and Encapsulation

25.1 Coating and Encapsulation Process

25.2 Coating and Encapsulation Inspection (Mandatory if 25.0 Coating and Encapsulation is checked)

26.0 Adhesive Bonding

27.0 Assembly Testing

27.4 In-Circuit Testing

27.5 Flying Probe Testing

27.8 Functional Testing

28.0 Final Acceptance Inspection

29.0 Rework

30.0 Storage, Handling & Packaging of Finished Goods